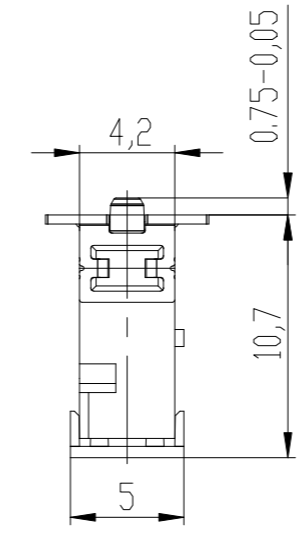
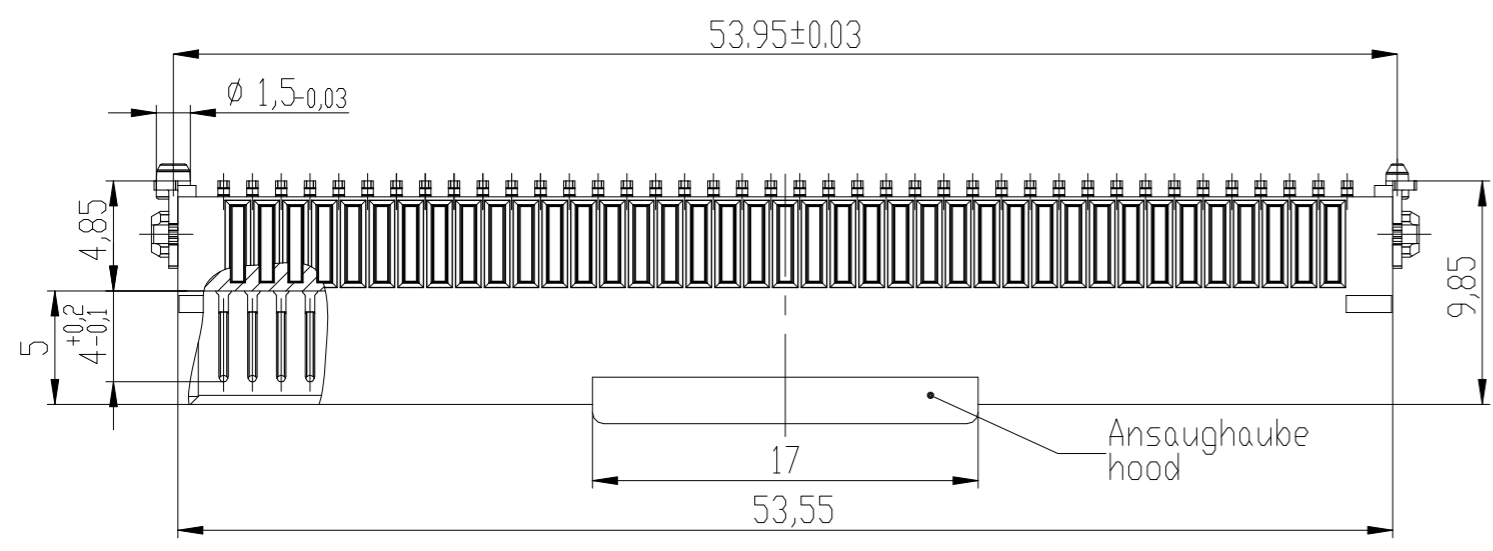
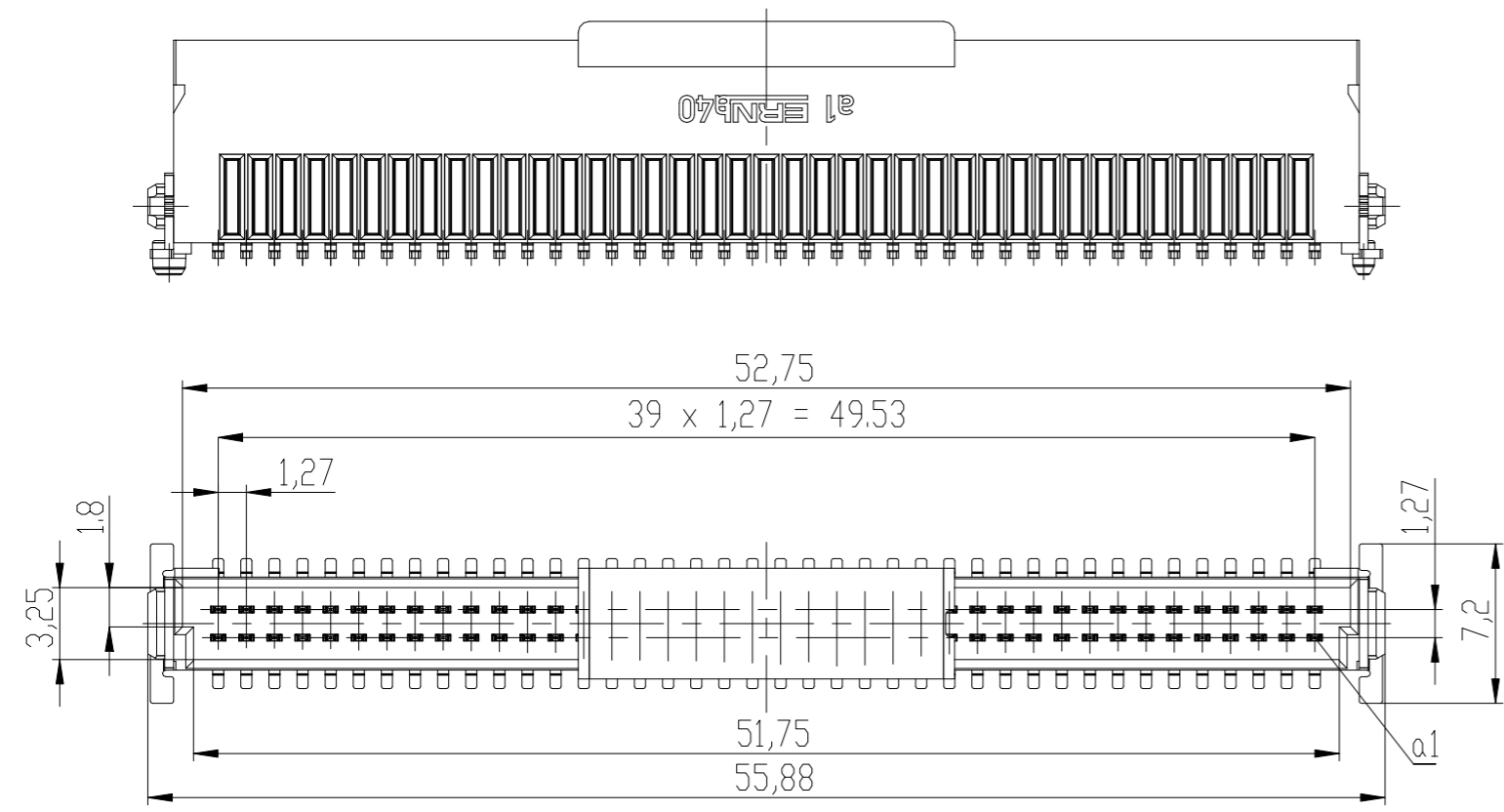
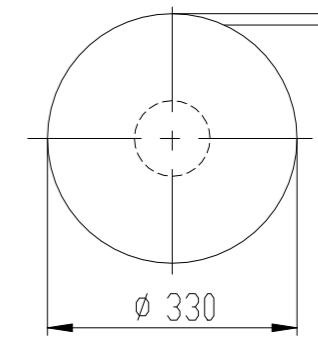
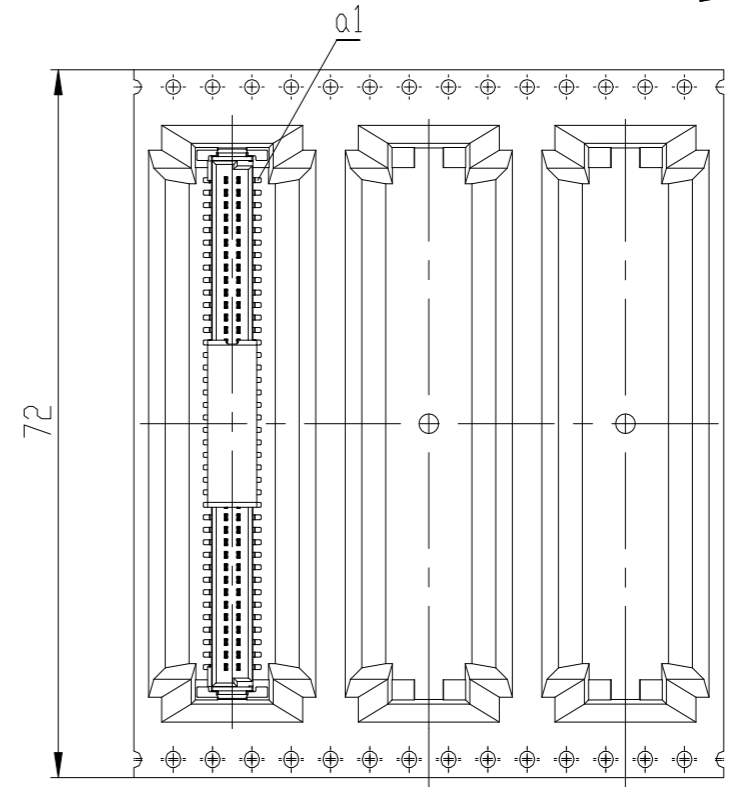


Anforderungsstufe 1
 performance level 1
 Kontaktbereich vergoldet
 mating area gold plating
 Anschlussbereich verzinkt 4-6 µm
 terminal area 4-6 µm tin plating
 Koplanarität der Anschlüsse ≤ 0,1 mm
 coplanarity area of termination ≤ 0,1 mm

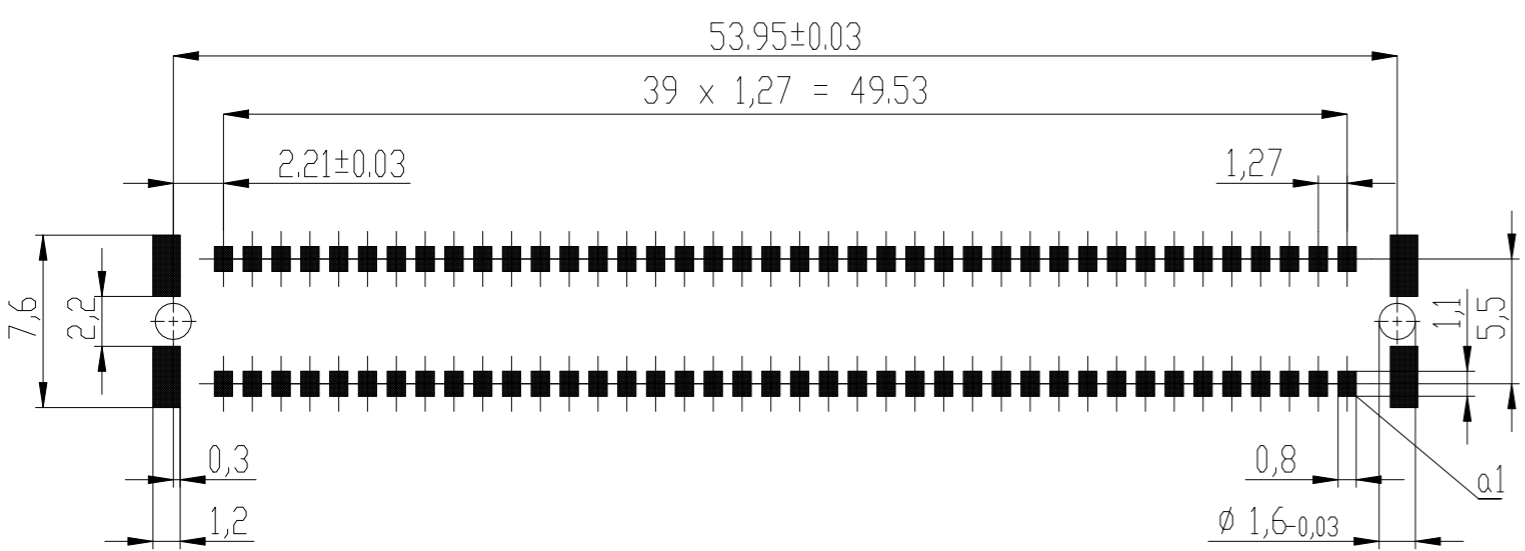
Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
 tape on reel packaging according to DIN IEC 60286-3
 Verpackungseinheit: 240 Stück
 packaging unit: 240 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT
 PCB-Layout Proposal for SMT



BA 8-23 - hohe Bauhöhe
 type 8-23 - High Profile

Information:	Tolerances	 All Dimensions in mm	Scale 3:1
	Customer drawing:		Designation
THIS DRAWING IS A CONTROLLED DOCUMENT.	Subject to modification without prior notice. Drawing will not be updated.	ERNI-Messerl. SMC-Q 80-SMD-BA8-23 Male SMC-Q 80-SMD-type8-23	
 TE Connectivity		 234210-E	I A3
f	30.10.2018	Class	SMCQ
Index	Date		

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)